nexperia

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023 Based on structural similarity

Supplier User Part Number Nexperia B.V. BZX585-B18-Q Name of Laboratory Part Description Nexperia DHAM Zener Assembly reliability labs SMD package Based on AEC-Q101 Test Test Conditions Duration # Lots # Querestimation FEST Pre- and Post-Stress Fest Conditions Duration # Lots # Querestimation JESD22-A113 Bake Tamb = 25 °C N/A see below all particular	
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) ()
MII-STD-750-1	
HTRB M1038 Method A High Temperature Reverse Tj = Tjmax, VR = 80 % of rated reverse	
B1 Bias voltage 1000 hours 250 11400) 0
MIL-STD-750-1	0
M1038 Method B	
SSOP Tj = Tjmax, $Iz = 100\%$ of max. datasheet	
# B1b Steady State Operational reverse current 1000 hours 44 1920	0
TC JESD22-A104	
# A4 Temperature Cycling -65 °C to Tjmax, not to exceed 150°C 1000 cycles 311 14080	0 0
UHAST JESD22-A118	
# A3 or Unbiased HAST Tamb = 130 °C, RH = 85 % 96 hours 311 14080	0
JESD22-A102	
AC Tamb = 121 °C, RH = 100 %	
# A3 alt Autoclave Pressure = 205 kPa (29.7 psia)	
H3TRB JESD22-A101	
H3TRB JESD22-A101 High Humidity High Tamb = 85 °C, RH = 85%, VR = 80 % of	
A2 alt Temperature Reverse Bias rated reverse voltage ^[1] 1000 hours 311 1408() 0
MIL-STD-750 Method 1037	. 0
IOL ton = toff, devices powered to insure $\Delta T_j =$	
# A5 Intermittent Operating Life 100 °C for 15000 cycles 1000 hours 312 14120	0 0
	-
RSH JESD22-A111	
# C8 Resistance to Solder Heat 260 °C ± 5 °C 10 s 269 8070	0
SD	
# C10 Solderability J-STD-002 19 6660	0

[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

(FIT) MTTF (hrs)
2,68E+09

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